

R5463Kxxxxx SERIES

EA-262-120711

OUTLINE

The R5463Kxxxxx Series are high voltage CMOS-based protection ICs for over-charge/discharge of two-cell Lithium-ion (Li+) / Lithium polymer, further include a short circuit protection circuit for preventing large external short circuit current and the protection circuits against the excess discharge-current and excess charge current.

Each of these ICs is composed of six voltage detectors, a reference unit, a delay circuit, a short circuit protector, an oscillator, a counter, and a logic circuit. When the over-charge voltage threshold or excess-charge current threshold crosses the each detector threshold from a low value to a high value, the output of Cout pin switches to "L" level after internal fixed delay time. To release over-charge detector after detecting over-charge, the detector can be reset and the output of Cou⊤ becomes "H" when a kind of load is connected to VDD after a charger is disconnected from the battery pack and the cell voltage becomes lower than over-charge detector threshold. In case that a charger is continuously connected to the battery pack, if the cell voltage becomes lower than the over-charge released voltage, over-charge state is also released.

The output of Dout pin, the output of the over-discharge detector and the excess discharge-current detector, switches to "L" level after internally fixed delay time, when discharged voltage crosses the detector threshold from a high value to a value lower than V_{DET2}. To release over-discharge detector, after detecting over-discharge voltage, connect a charger to the battery pack, and when the battery supply voltage becomes higher than the over-discharge detector threshold, the over-discharge detector is released and the voltage of DOUT pin becomes

If the battery is discharged lower than maximum voltage for inhibition of charger, recharge current is not acceptable.

After detecting excess-discharge current or short current, when the load is disconnected, the excess discharged or short condition is released and Dout becomes "H".

After detecting over-discharge voltage, supply current will be kept extremely low by halting internal circuits' operation.

When the output of COUT is "H", if V- pin level is set at -1.6V, the delay time of over-charge and over-discharge detector can be shortened. Especially, the delay time of the over-charge detector can be reduced into approximately 1/60 and test time for protection circuit PCB can be reduced. The output type of COUT and DOUT is CMOS.

R5463Kxxxxx

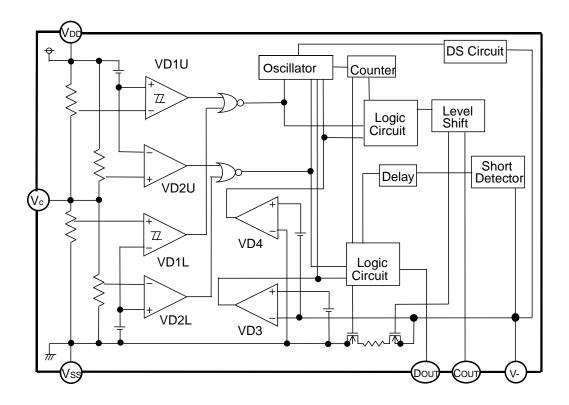
FEATURES

Manufactured with High Voltage Tolerant Process	s Absolute Maximum Rating			30V
Low supply current	Supply current (At normal mo	de)		Typ. 4.0µA
	Standby current			Max. 0.1μA
High accuracy detector threshold	Over-charge detector	(Ta=25°C	()	±20mV
		(Ta=-5°C	to 55°C)	±25mV
	Over-discharge detector			±1.0%
	Excess discharge-current dete	ctor	(G ver.)	±10mV
			(J ver.)	±10%
	Excess charge-current detector	or		±20mV
Variety of detector threshold	Over-charge detector threshold		3.65V-4.3	2V step of 0.005V
	Over-discharge detector threshold		2.0V-3.2V	step of 0.005V
E	Excess discharge-current threshold	I (G ver.)	0.05V-0.2	0V step of 0.005V
		(J ver.)	0.20V-0.4	0V step of 0.005V
E	Excess charge-current threshold		-0.2V0.1	V step of 0.005V
Internal fixed Output delay time	Over-charge detector Output D	Delay		1s
	Over-discharge detector Output	ut Delay		128ms
	Excess discharge-current dete	ctor Outp	ut Delay	12ms
	Excess charge-current detector	r Output	Delay	8ms
	Short Circuit detector Output D	Pelay		300µs
Output Delay Time Shortening Function	At COUT is "H", if V- level is se	et at -1.6\	V, the Out	put Delay time of
	detect the over-charge and over	er-dischaı	rge can be	e reduced.
	(Delay Time for over-charge be	ecomes a	bout 1/60	of normal state.)
0V-battery charge	Unacceptable			
Ultra Small package	DFN(PLP)1820-6B			

APPLICATIONS

- Li+ / Li Polymer protector of over-charge, over-discharge, excess-current for battery pack
- High precision protectors for cell-phones and any other gadgets using on board Li+ / Li Polymer battery

BLOCK DIAGRAMS



SELECTION GUIDE

In the R5463Kxxxxx Series, input threshold of over-charge, over-discharge, excess discharge current, and the package and taping can be designated.

Part Number is designated as follows:

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free	
R5463K2xx\$*-TR	DFN(PLP)1820-6B	5,000pcs	Yes	Yes	

xx :Serial Number for the R5463K Series designating voltages such as over-charge threshold, over-charge, over-discharge threshold, over-discharge current, over-charge current, short voltage.

\$: Designation of Output delay time option.

	Over-charge	Over-discharge	Over-discharge Current	Over-charge Current	Short
	Delay time	Delay time	Delay time	Delay time	Delay time
	(s)	(ms)	(ms)	(ms)	(μs)
R5463KxxxA*	1.0	128	12	8	300

* : Designation of protection type.

	Over-charge Released condition	Over-discharge Released condition	0V battery Charge	Adustable Range of Excess Charge-current Threshold
R5463Kxxx\$G	Auto Release	Latch	NG	0.05 to 0.20V
R5463Kxxx\$J	Auto Release	Latch	NG	0.20 to 0.40V

PRODUCT NAME LIST

Code	VDET1 (V)	VREL1 (V)	VDET2 (V)	VREL2 (V)	VDET3 (V)	VDET4 (V)
R5463K217AG	4.280	4.080	2.000	-	0.200	-0.100
R5463K221AJ	4.300	4.100	2.600	-	0.370	-0.160
R5463K224AG	4.280	4.080	2.000	_	0.110	-0.100

PIN CONFIGURATIONS

DFN(PLP)1820-6B



PIN DESCRIPTION

Pin No.	Symbol	Pin Description
1	Соит	Output pin of over-charge detection, CMOS output
2	V-	Pin for charger negative input
3	D оит	Output pin of over-discharge detection, CMOS output
4	Vss	Vss pin. Ground pin for the IC
5	V _{DD}	Power supply pin, the substrate voltage level of the IC.
6	VC	Input Pin of the center voltage between two-cell

The backside tab of DFN(PLP)1820-6B package is connected to the substrate level. (VDD) Note that avoiding short with other level.

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Ratings	Unit
V _{DD}	Supply voltage	-0.3 to 12	V
	Input Voltage		
Vc	Center pin voltage between two-cell	Vss -0.3 to VDD+0.3	V
V-	Charger negative input V- pin	VDD -30 to VDD+0.3	V
	Output voltage		
VCоит	Соит pin	V _{DD} -30 to V _{DD} +0.3	V
VDоит	Dout pin	Vss -0.3 to Vdd +0.3	V
PD	Power dissipation	150	mW
Ta	Operating temperature range	-40 to 85	°C
Tstg	Storage temperature range	-55 to 125	ပ္

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

ELECTRICAL CHARACTERISTICS

R5463KxxxAG

Unless otherwise specified Ta=25°C

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Operating Input Voltage	V _{DD1}	V _{DD} -V _{SS}	1.5	71	10	V
Maximum Operating Voltage for Inhibition of Charger	Vnochg	V _{DD} -V _C or V _C -V _{SS}	0.6	0.8	1.0	V
Cell1 Over-charge Detector Threshold	V _{DET1U}	R1=330 Ω R1=330 Ω , (Ta=-5°C to 55°C)*Note1	VDET1U-0.020 VDET1U-0.025	V _{DET1U}	VDET1U+0.020 VDET1U+0.025	V
Cell1 Over-charge Released Voltage	V _{REL1U}	R1=330Ω	V _{REL1U} -0.050	V _{REL1U}	V _{REL1U} +0.050	V
Cell2 Over-charge Detector threshold	V _{DET1L}	R2=330Ω R2=330Ω, (Ta=-5°C to 55°C)*Note1	VDET1L-0.020 VDET1L-0.025	V _{DET1L}	VDET1L+0.020 VDET1L+0.025	V
Cell2 Over-charge Released Voltage	V _{REL1L}	R2=330Ω	V _{REL1L} -0.050	V _{REL1L}	V _{REL1L} +0.050	V
Output Delay of Over-charge	tV _{DET1}	V_{DD} - V_{C} =3.5V to 4.5V V_{C} - V_{SS} =3.5V	0.7	1.0	1.3	s
Output Delay of Release from Over-charge	tV _{REL1}	V_{DD} - V_{C} =4.5V to 3.5V, V_{C} - V_{SS} =3.5V	11	16	21	ms
Cell1 Over-discharge Threshold	VDET2U	Detect falling edge of the input voltage	V _{DET2U} × 0.990	V _{DET2U}	V _{DET2U} × 1.010	V
Cell2 Over-discharge Threshold	V _{DET2L}	Detect falling edge of the input voltage	VDET2L × 0.990	V _{DET2L}	VDET2L × 1.010	V
Output Delay of Over-discharge	tV _{DET2}	V_{DD} - V_{C} =3.5V to 1.5V V_{C} - V_{SS} =3.5V	89	128	167	ms
Output Delay of Release from Over-discharge	tV _{REL2}	V_{DD} - V_{C} =1.5V to 3.5V V_{C} - V_{SS} =3.5V	0.7	1.2	1.7	ms
Excess Discharge-current Threshold	V _{DET3}	Detect rising edge of 'V-' pin voltage	VDET3-0.010	V _{DET3}	VDET3+0.010	V
Output Delay of Excess Discharge-current	tV _{DET3}	V _{DD} -V _C =3.5V,V _C -V _{SS} =3.5V V-=0V to 0.5V	8	12	16	ms
Output Delay of Release from Excess Discharge-current	tV _{REL3}	V _{DD} -V _C =3.5V,V _C -V _{SS} =3.5V V-=3V to 0V	0.7	1.2	1.7	ms
Short Protection Voltage	Vshort	V _{DD} -V _C =3.5V,V _C -V _{SS} =3.5V	0.6	1.0	1.4	V
Delay Time for Short Protection	t short	V _{DD} -V _C =3.5V,V _C -V _{SS} =3.5V V-=0V to 1.5V	150	300	500	μs
Reset Resistance for Excess Current Protection	Rshort	V _{DD} -V _C =3.6V,V _C -V _{SS} =3.6V V-=1V	25	40	75	kΩ
Excess Charge-current Threshold	V _{DET4}	Detect falling edge of 'V-' pin voltage	VDET4-0.020	V _{DET4}	V _{DET4} +0.020	V
Output Delay of Excess Charge-current	tV _{DET4}	V _{DD} -V _C =3.5V, V _C -V _{SS} =3.5V V-=0V to -1V	5	8	11	ms
Output Delay of Release from Excess Charge-current	tV _{REL4}	V _{DD} -V _C =3.5V, V _C -V _{SS} =3.5V V-=-1V to 0V	0.7	1.2	1.7	ms
Delay Shortening Mode Voltage	V _{DS}	V _{DD} -V _C =4.4V, V _C -V _{SS} =4.4V	-2.2	-1.6	-1.0	V
Nch ON-Voltage of C _{OUT}	V _{OL1}	IoI=50µA, V _{DD} -V _C =4.5V V _C -V _{SS} =4.5V		0.4	0.5	V
Pch ON-Voltage of Cout	V он1	loh=-50µA, V _{DD} -V _C =3.9V V _C -V _{SS} =3.9V	6.8	7.4		V
Nch ON-Voltage of D _{OUT}	V _{OL2}	lol=50µA, V _{DD} -V _C =1.9V V _C -V _{SS} =1.9V		0.2	0.5	V
Pch ON-Voltage of Dout	V _{OH2}	loh=-50µA, V _{DD} -V _C =3.9V V _C -V _{SS} =3.9V	6.8	7.4		V
Supply Current	loo	V _{DD} -V _C =3.9V, V _C -V _{SS} =3.9V V-=0V		4.0	8.0	μА
Standby Current	Іѕтв	V _{DD} -V _C =1.9V, V _C -V _{SS} =1.9V			0.1	μА

^{*}Note1: Considering of variation in process parameters, we compensate for this characteristic related to temperature by laser-trim, however, this specification is guaranteed by design, not tested.

R5463KxxxAJ

Unless otherwise specified Ta=25°C

TO-TO-TRAKANO Offices officially in a specified ta=25 C							
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Operating Input Voltage	V _{DD1}	V _{DD} -V _{SS}	1.5		10	V	
Maximum Operating Voltage for Inhibition of Charger	Vnochg	V _{DD} -V _C or V _C -V _{SS}	0.6	0.8	1.0	V	
Cell1 Over-charge Detector Threshold	V _{DET1U}	R1=330 Ω R1=330 Ω , (Ta=-5°C to 55°C) *Note1	V _{DET1U} -0.020 V _{DET1U} -0.025	V _{DET1U}	V _{DET1U} +0.020 V _{DET1U} +0.025	V	
Cell1 Over-charge Released Voltage	V _{REL1U}	R1=330Ω	V _{REL1U} -0.050	V _{REL1U}	V _{REL1U} +0.050	V	
Cell2 Over-charge Detector threshold	V _{DET1L}	R2=330Ω R2=330Ω, (Ta=-5°C to 55°C)*Note1	VDET1L-0.020 VDET1L-0.025	V _{DET1L}	VDET1L+0.020 VDET1L+0.025	V	
Cell2 Over-charge Released Voltage	V _{REL1L}	R2=330Ω	V _{REL1L} -0.050	V _{REL1L}	V _{REL1L} +0.050	V	
Output Delay of Over-charge	tV _{DET1}	V_{DD} - V_{C} =3.5V to 4.5V V_{C} - V_{SS} =3.5V	0.7	1.0	1.3	s	
Output Delay of Release from Over-charge	tV _{REL1}	V_{DD} - V_{C} =4.5V to 3.5V, V_{C} - V_{SS} =3.5V	11	16	21	ms	
Cell1 Over-discharge Threshold	V _{DET2U}	Detect falling edge of the input voltage	V _{DET2U} × 0.990	V _{DET2U}	V _{DET2U} × 1.010	V	
Cell2 Over-discharge Threshold	V _{DET2L}	Detect falling edge of the input voltage	VDET2L × 0.990	VDET2L	VDET2L × 1.010	V	
Output Delay of Over-discharge	tV _{DET2}	V_{DD} - V_{C} =3.5V to 1.5V V_{C} - V_{SS} =3.5V	89	128	167	ms	
Output Delay of Release from Over-discharge	tV _{REL2}	V_{DD} - V_{C} =1.5V to 3.5V V_{C} - V_{SS} =3.5V	0.7	1.2	1.7	ms	
Excess Discharge-current Threshold	V _{DET3}	Detect rising edge of 'V-' pin voltage	VDET3 × 0.900	V _{DET3}	VDET3 × 1.100	V	
Output Delay of Excess Discharge-current	tVdet3	V _{DD} -V _C =3.5V,V _C -V _{SS} =3.5V V-=0V to 0.5V	8	12	16	ms	
Output Delay of Release from Excess Discharge-current	tV _{REL3}	V_{DD} - V_{C} =3.5 V , V_{C} - V_{SS} =3.5 V	0.7	1.2	1.7	ms	
Short Protection Voltage	VSHORT	$V_{DD}-V_{C}=3.5V, V_{C}-V_{SS}=3.5V$	0.6	1.0	1.4	V	
Delay Time for Short Protection	t short	V_{DD} - V_{C} =3.5 V , V_{C} - V_{SS} =3.5 V	150	300	500	μs	
Reset Resistance for Excess Current Protection	Rshort	V _{DD} -V _C =3.6V,V _C -V _{SS} =3.6V V-=1V	25	40	75	kΩ	
Excess Charge-current Threshold	V _{DET4}	Detect falling edge of 'V-' pin voltage	VDET4-0.020	VDET4	VDET4+0.020	V	
Output Delay of Excess Charge-current	tV _{DET4}	V_{DD} - V_{C} =3.5V, V_{C} - V_{SS} =3.5V V-=0V to -1V	5	8	11	ms	
Output Delay of Release from Excess Charge-current	tV _{REL4}	V_{DD} - V_{C} =3.5V, V_{C} - V_{SS} =3.5V V-=-1V to 0V	0.7	1.2	1.7	ms	
Delay Shortening Mode Voltage	VDS	V _{DD} -V _C =4.4V, V _C -V _{SS} =4.4V	-2.2	-1.6	-1.0	V	
Nch ON-Voltage of Cout	V _{OL1}	Iol=50µA, V _{DD} -V _C =4.5V V _C -V _{SS} =4.5V		0.4	0.5	V	
Pch ON-Voltage of Cout	V _{OH1}	loh=- 50μ A, V_{DD} - V_{C} = $3.9V$ V_{C} - V_{SS} = $3.9V$	6.8	7.4		V	
Nch ON-Voltage of Dout	V _{OL2}	$IoI=50\mu A, V_{DD}-V_{C}=1.9V$ $V_{C}-V_{SS}=1.9V$		0.2	0.5	V	
Pch ON-Voltage of Dout	V _{OH2}	loh=- 50μ A, V_{DD} - V_{C} = $3.9V$ V_{C} - V_{SS} = $3.9V$	6.8	7.4		V	
Supply Current	loo	V _{DD} -V _C =3.9V, V _C -V _{SS} =3.9V V-=0V		4.0	8.0	μА	
Standby Current	Іѕтв	V _{DD} -V _C =1.9V, V _C -V _{SS} =1.9V			0.1	μΑ	

*Note1: Considering of variation in process parameters, we compensate for this characteristic related to temperature by laser-trim, however, this specification is guaranteed by design, not tested.

OPERATION

• VDET1U, VDET1L / Over-Charge Detectors

The VDET1U and VDET1L monitor the voltage between V_{DD} pin and V_c pin (the voltage of Cell1) and the voltage between V_C pin and V_{SS} pin (the voltage of Cell2), if either voltage becomes equal or more than the over-charge detector threshold, the over-charge is detected, and an external charge control Nch MOSFET turns off with C_{OUT} pin being at "L" level.

VDET1U is the detector of Cell1, and the VDET1L is the detector of Cell2.

To reset the over-charge and make the Cout pin level to "H" again after detecting over-charge, in such conditions that a time when the both Cell1 and Cell2 are down to a level lower than over-charge voltage, by connecting a kind of load to Vdd after disconnecting a charger from the battery pack. Then, the output voltage of Cout pin becomes "H", and it makes an external Nch MOSFET turn on, and charge cycle is available. In case of the charger is continuously connected and over-charge is detected, both battery voltages of Cell1 and Cell2 become lower than the released voltage from over-charge, charge becomes possible. Therefore there is a specific hysteresis for over-charge detectors. To judge whether or not load is connected, the built-in excess-discharge current detector is used. By connecting some load, V- pin voltage becomes equal or more than excess-discharge current detector threshold, and reset the over-charge detecting state.

Further, either or both voltage of Cell1 and Cell2 is higher than the over-charge detector threshold, if a charger is removed and some load is connected, Cout outputs "L", however, load current can flow through the parasitic diode of the external charge control Nch MOSFET. After that, when both voltages of Cell1 and Cell2 become lower than the over-charge detector threshold, Cout becomes "H".

Internal fixed output delay times for over-charge detection and release from over-charge exist. If either or both of the voltage of Cell1 or Cell2 keeps its level more than the over-charge detector threshold, and output delay time passes, over-charge voltage is detected. Even when the voltage of Cell1 or Cell2 pin level becomes equal or higher level than V_{DET1} if these voltages would be back to a level lower than the over-charge detector threshold within a time period of the output delay time, the over-charge is not detected. Besides, after detecting over-charge, while the both of Cell1 and Cell2 voltages are lower than the over-charge detector threshold, even if a charger is removed and a load is connected, if the voltage is recovered within output delay time of release from over-charge, over-charge state is not released.

A level shifter incorporated in a buffer driver for the Cout pin makes the "L" level of Cout pin to the V - pin voltage and the "H" level of Cout pin is set to VDD voltage with CMOS buffer.

VDET2U, VDET2L / Over-Discharge Detectors

The VDET2U and VDET2L monitor the voltage between V_{DD} pin and Vc pin (Cell1 voltage) and the voltage between Vc pin and Vss pin (Cell2 Voltage). When either of the Cell1 or Cell2 voltage becomes equal or less than the over-discharge detector threshold, the over-discharge is detected and discharge stops by the external discharge control Nch MOSFET turning off with the D_{OUT} pin being at "L" level.

To reset the over-discharge detector, connecting a charger is the only method. When the charger is connected,

if Cell1 or Cell2 is less than the over-discharge detector threshold, a charge current flows through the parasitic diode of the external MOSFET. Then, the voltages of Cell1 and Cell2 become higher than the released voltage from over-discharge, Dout becomes "H" and the external MOSFET turns on and discharge will be possible. When a charger is connected, when the Cell1 and Cell2 voltages become equal or more than the over-discharge detector threshold, the over-discharge is released and the voltage of the Dout pin becomes "H" after the delay time.

When either Cell1 or Cell2 voltage is equal or less than the maximum voltage for inhibition of charger (Vnochg), even if a charger is connected to the battery pack, Cout pin is stacked with "L" and the system is not allowable for charge.

The output delay time for over-discharge detect is fixed internally. Even if the voltage of Cell1 or Cell2 is down to equal or lower than the over-discharge detector threshold, if the both voltages of Cell1 and Cell2 would be back to a level higher than the over-discharge detector threshold within a time period of the output delay time, the over-discharge is not detected. Output delay time for release from over-discharge is also set.

After detecting over-discharge, supply current would be reduced and be into standby by halting all the circuits and consumption current of the IC itself is made extremely low.

The output type of Dout pin is CMOS having "H" level of VDD and "L" level of VSS.

VDET3 /Excess discharge-current Detector, Short Circuit Protector

Both of the excess current detector and short circuit protection can work when the both of control FETs are in "ON" state.

When the V- pin voltage is up to a value between the short protection voltage Vshort and excess discharge-current threshold V_{DET3}, VDET3 operates and further soaring of V- pin voltage higher than Vshort makes the short circuit protector enabled. This leads the external discharge control Nch MOSFET turns off with the D_{OUT} pin being at "L" level.

An output delay time for the excess discharge-current detector is internally fixed. A quick recovery of V- pin level from a value between Vshort and V_{DET3} within the delay time keeps the discharge control FET staying "H" state. Output delay time for Release from excess discharge-current detection is also set.

When the short circuit protector is enabled, the Dout would be "L" and the delay time is also set.

The V - pin has a built-in pull-down resistor to the Vss pin, that is, the resistance to release from excess-discharge current. After an excess discharge-current or short circuit protection is detected, removing a cause of excess discharge-current or external short circuit makes an external discharge control FET to an "ON" state automatically with the V- pin level being down to the Vss level through the built-in pulled down resistor. The reset resistor of excess discharge-current is off at normal state. Only when detecting excess discharge-current or short circuit, the resistor is on.

Output delay time of excess discharge-current is set shorter than the delay time for over-discharge detector. Therefore, if V_{DD} voltage would be lower than V_{DET2} at the same time as the excess discharge-current is detected, the R5463Kxxxxx is at excess discharge-current detection mode. By disconnecting a load, VDET3 is automatically released from excess discharge-current.

R5463Kxxxxx

VDET4/ Excess charge-current detector

When the battery pack is chargeable and discharge is also possible, VDET4 senses V- pin voltage. For example, in case that a battery pack is charged by an inappropriate charger, an excess current flows, then the voltage of V- pin becomes equal or less than excess charge-current detector threshold. Then, the output of Cout becomes "L", and prevents from flowing excess current in the circuit by turning off the external Nch MOSFET.

Output delay of excess charge current is internally fixed. Even the voltage level of V- pin becomes equal or lower than the excess charge-current detector threshold, the voltage is higher than the VDET4 threshold within the delay time, the excess charge current is not detected. Output delay for the release from excess charge current is also set.

VDET4 can be released with disconnecting a charger and connecting a load.

• DS (Delay Shorten) function

Output delay time of over-charge, over-discharge can be shorter than those setting value by forcing equal or less than the delay shortening mode voltage to V- pin when the COUT is "H".

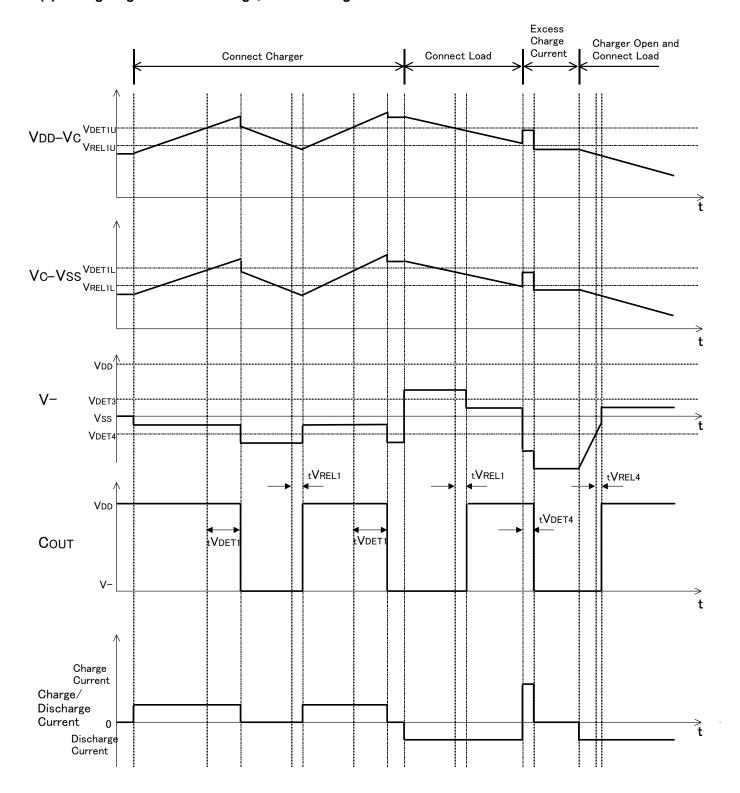
• Operation against 2-Cell Unbalance

If one of the cells detects over-charge, and when the COUT becomes "L", even if the other cell would detect over-discharge, the over-charge detector will be dominant and COUT keeps the "L" level. If one of the cells detects the over-discharge, and when the DOUT becomes "L", in case that a charger is connected to the battery pack and the other cell detects over-charge, the internal counter will start and after the delay time of over-discharge detector, DOUT will become "H". After the delay time of over-charge release from when the internal counter starts, COUT will be "L". If the over-discharge is detected, internal unnecessary circuits will be cut off and the standby mode will be realized. (Standby current Max. 0.1µA)

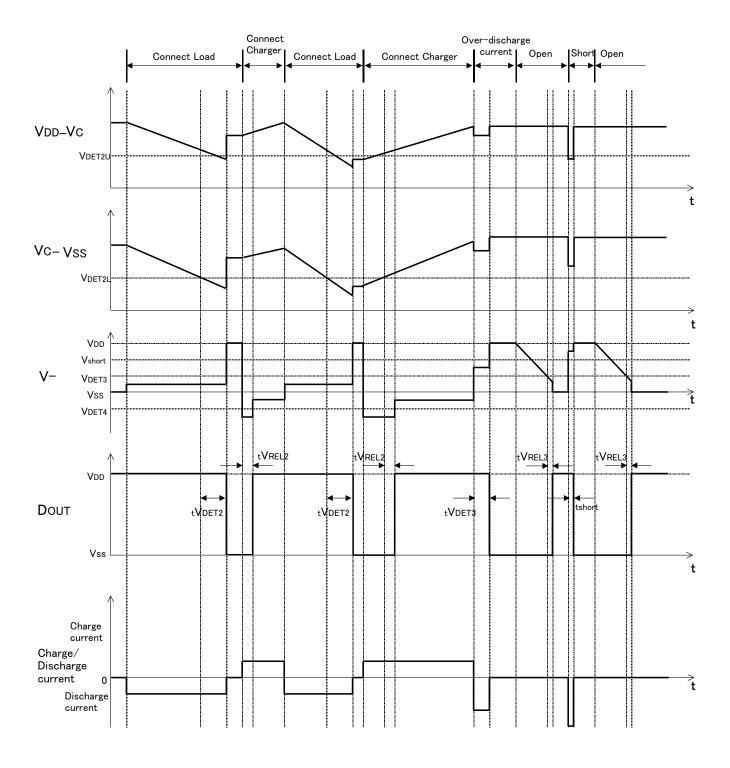
In any versions, the external FETs do not turn off at the same time.

TIMING CHART

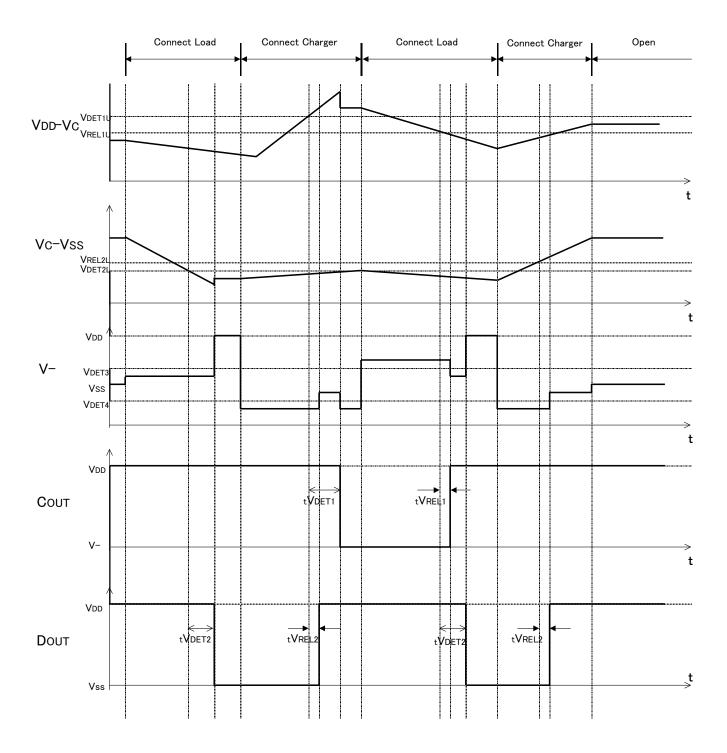
(1) Timing diagram of Over-charge, Excess charge current



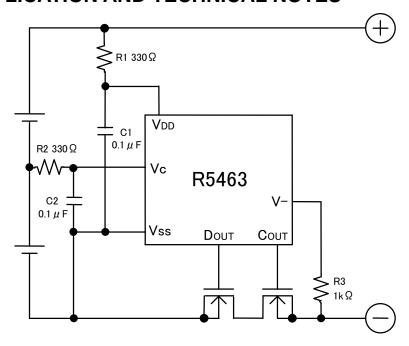
(2) Over-discharge, Excess discharge current, Short circuit



(3) Operation with unbalanced cells



TYPICAL APPLICATION AND TECHNICAL NOTES



TECHNICAL NOTES

R1, R2, C1 and C2 stabilize a supply voltage to the R5463. A recommended R1, R2 value is less than $1k\Omega$. A larger value of R1 and R2 makes the detection voltage shift higher because of some conduction current in the R5463.

To stabilize the operation, the value of C1 and C2 should be equal or more than 0.01μF.

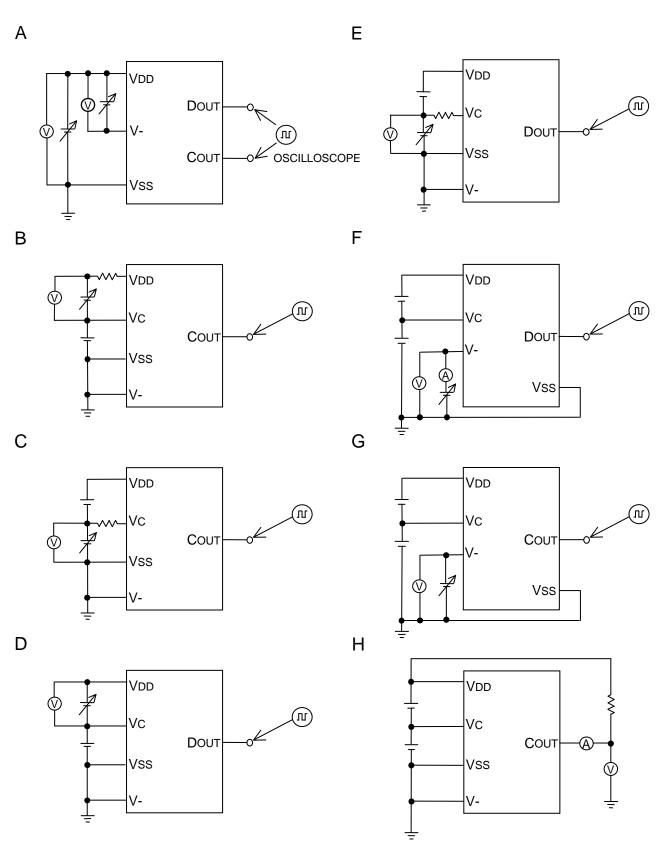
R1 and R3 can operate also as parts for current limit circuit against reverse charge or applying a charger with excess charging voltage beyond the absolute maximum rating of the R5463, the battery pack. Small value of R1 and R3 may cause over-power consumption rating of power dissipation of the R5463. Thus, the total value of 'R1+R3' should be equal or more than $1k\Omega$. If a large value of R3 is set, after detecting over-discharge, the release by connecting a charger may not be possible. Therefore, recommendation value of R3 is equal or less than $3k\Omega$.

The typical application circuit diagram is just an example. This circuit performance largely depends on the PCB layout and external components. In the actual application, fully evaluation is necessary.

Over-voltage and the over current beyond the absolute maximum rating should not be forced to the protection IC and external components. Although the short protection circuit is built in the IC, if the positive terminal and the negative terminal of the battery pack are short, during the delay time of short limit detector, large current flows through the FET. Select an appropriate FET with large enough current capacity to prevent the IC from burning damage.

We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire-containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.

TEST CIRCUITS



I Vdd COUT Vc Vss J Vdd Vc DOUT Vss K VDD Dout Vc Vss L VDD Vc Vss

Typical Characteristics were obtained with using those above circuits:

Test Circuit A: Typical characteristics 1)

Test Circuit B: Typical characteristics 2) 4) 6) 7)

Test Circuit C: Typical characteristics 3) 5)
Test Circuit D: Typical characteristics 8) 10) 11)

Test Circuit E: Typical characteristics 9)

Test Circuit F: Typical characteristics 12) 13) 14) 15) 16) 17)

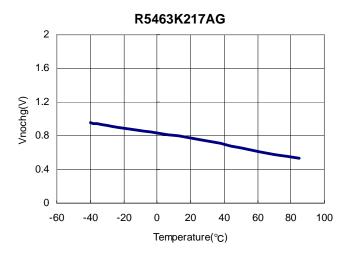
Test Circuit G: Typical characteristics 18) 19) 20) 21)

Test Circuit H: Typical characteristics 22)
Test Circuit I: Typical characteristics 23)
Test Circuit J: Typical characteristics 24)
Test Circuit K: Typical characteristics 25)
Test Circuit L: Typical characteristics 26) 27)

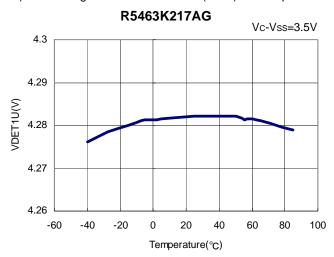
TYPICAL CHARACTERISTICS

Part 1

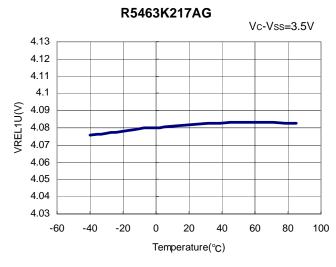
1) Maximum Operating Voltage for Inhibition of Charger vs. Temperature



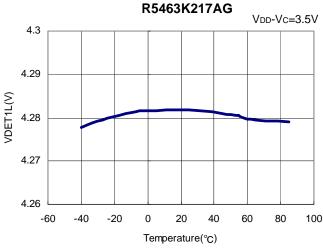
2) Over-charge Detector Threshold (Cell1) vs. Temperature



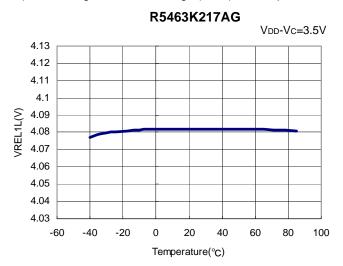
4) Over-charge Released Voltage (Cell1) vs. Temperature



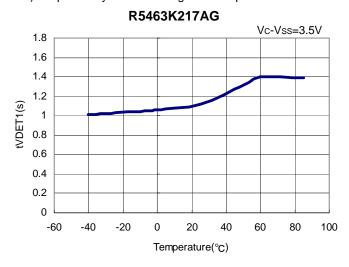
3) Over-charge Detector Threshold (Cell2) vs. Temperature



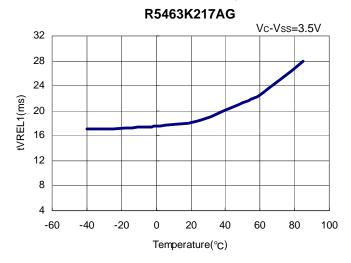
5) Over-charge Released Voltage (Cell2) vs. Temperature



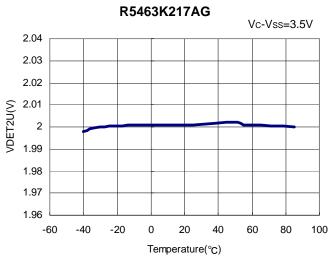
6) Output Delay of Over-charge vs. Temperature

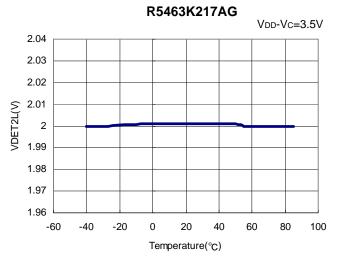


7) Output Delay of Release from Over-charge vs. Temperature

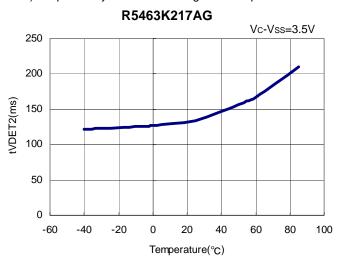


8) Over-discharge Detector Threshold (Cell1) vs. Temperature 9) Over-discharge Detector Threshold (Cell2) vs. Temperature

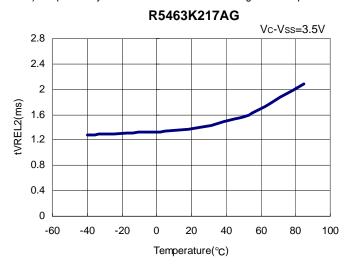




10) Output Delay of Over-discharge vs. Temperature

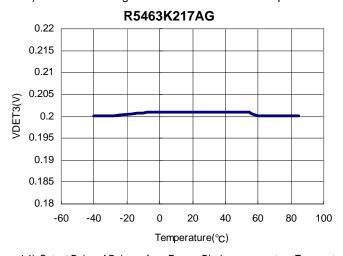


11) Output Delay of Release from Over-discharge vs. Temperature

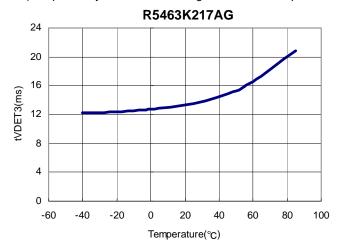


R5463Kxxxxx

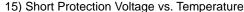
12) Excess Discharge-current Threshold vs. Temperature

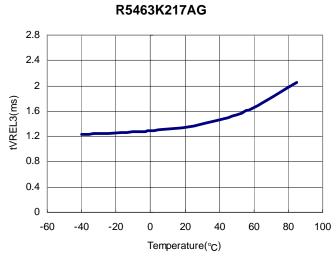


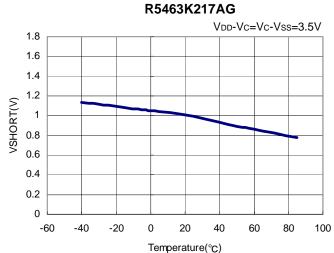
13) Output Delay of Excess Discharge-current vs. Temperature



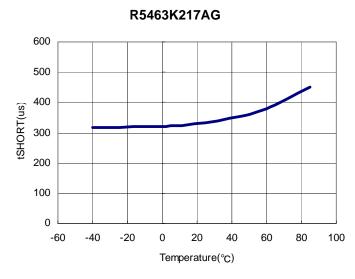
14) Output Delay of Release from Excess Discharge-current vs. Temperature 15) Short Protection Voltage vs. Temperature



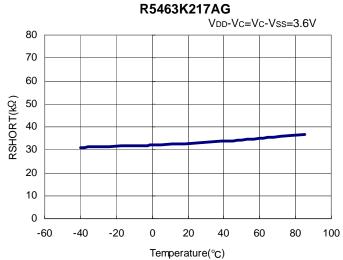




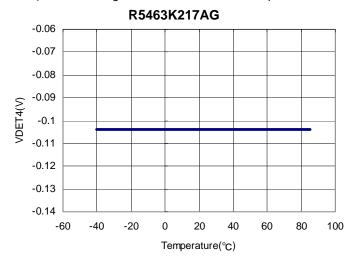
16) Delay Time for Short Protection vs. Temperature



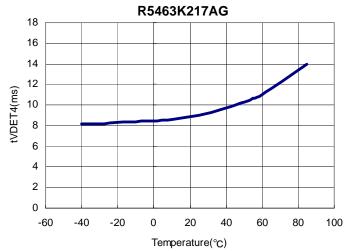
17) Reset Resistance for Excess Current Protection vs. Temperature



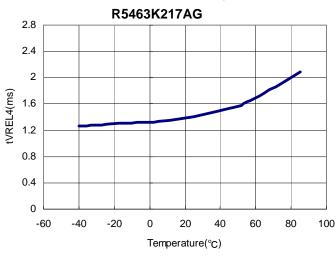
18) Excess Charge-current Threshold vs. Temperature

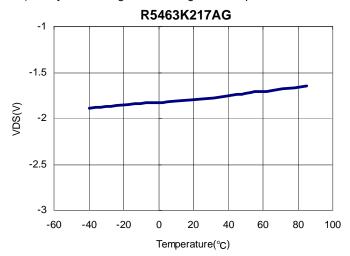


19) Output Delay of Excess Charge-current vs. Temperature

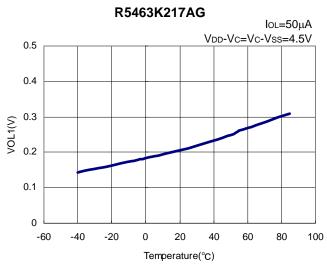


20) Output Delay of Release from Excess Charge-current vs. Temperature 21) Delay Shortening Mode Voltage vs. Temperature

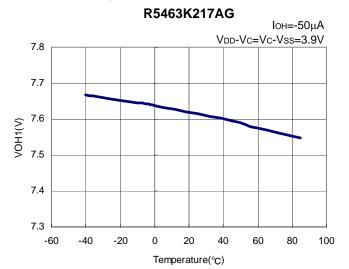




22) Nch ON-Voltage of Cout vs. Temperature

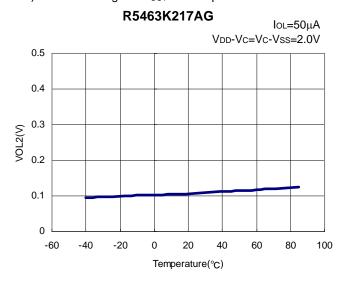


23) Pch ON-Voltage of Cout vs. Temperature

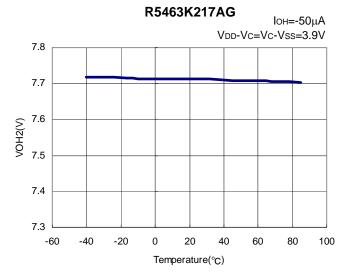


R5463Kxxxxx

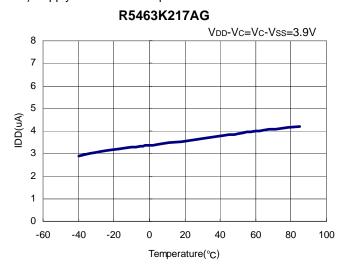
24) Nch ON-Voltage of D_{OUT} vs. Temperature



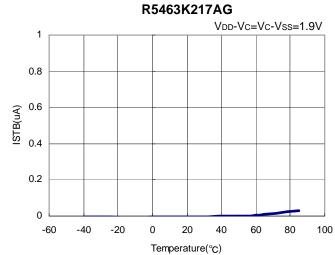
25) Pch ON-Voltage of D_{OUT} vs. Temperature



26) Supply Current vs. Temperature

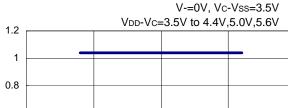


27) Standby Current vs. Temperature

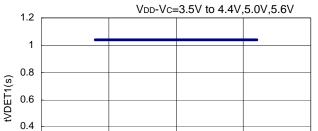


Delay Time dependence on VDD Part 2

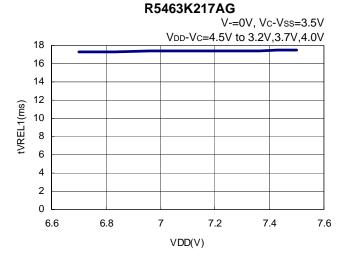
1) Output Delay of Over-charge vs. VDD



R5463K217AG



2) Output Delay of Release from Over-charge vs. VDD



3) Output Delay of Over-discharge vs. VDD

8

0.2

0 7.5

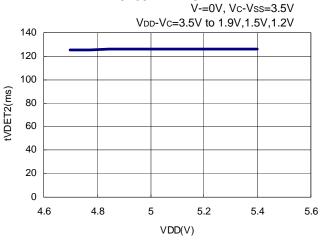
R5463K217AG

8.5

VDD(V)

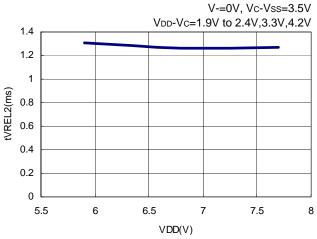
9

9.5



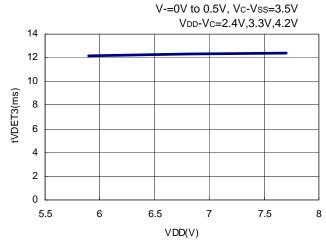
4) Output Delay of Release from Over-discharge vs. VDD





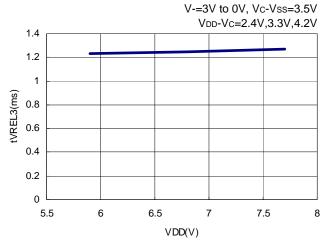
5) Output Delay of Excess Discharge-current vs. VDD

R5463K217AG



6) Output Delay of Release from Excess Discharge-current vs. VDD

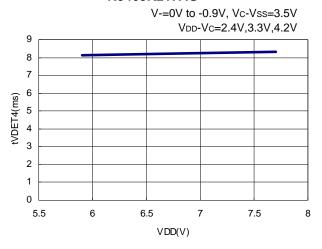
R5463K217AG



R5463Kxxxxx

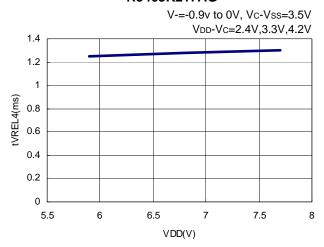
7) Output Delay of Excess Charge-current vs. VDD

R5463K217AG



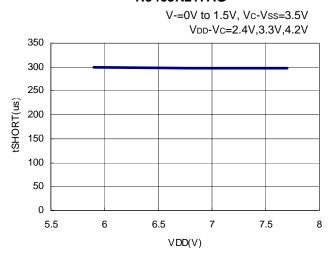
8) Output Delay of Release from Excess Charge-current vs. VDD

R5463K217AG



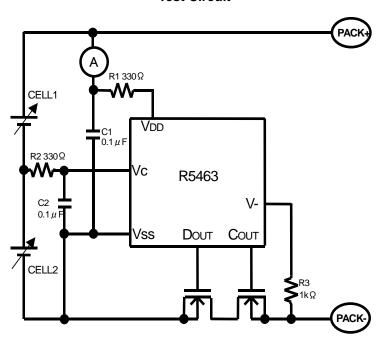
9) Delay Time for Short Protection vs. V_{DD}

R5463K217AG

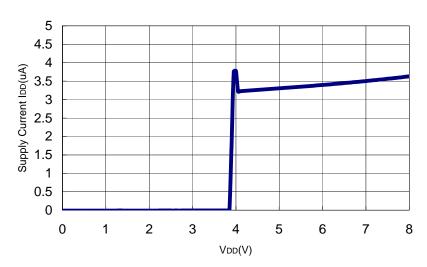


Part 3 Supply Current dependence on VDD

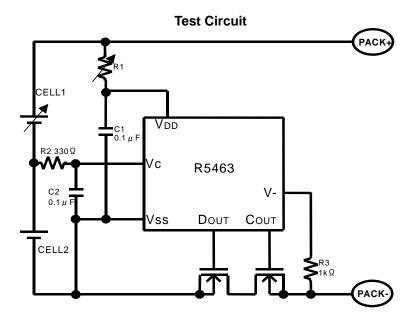
Test Circuit



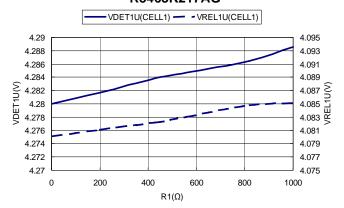
Supply Current vs. VDD



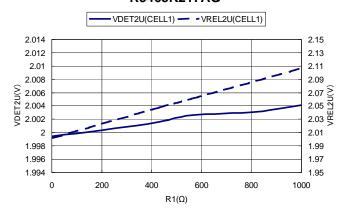
Part 4 Over-charge detector, Release voltage from Over-charge, Over-discharge detector, Release voltage from Over-discharge dependence on External Resistance value



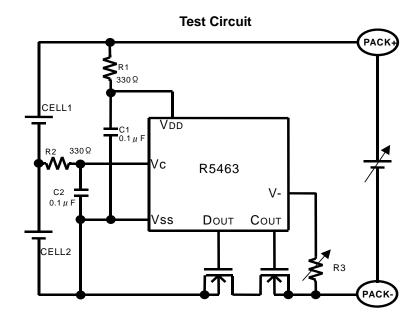
Over-charge Detector Threshold / Released Voltage from Over-charge vs. R1 R5463K217AG



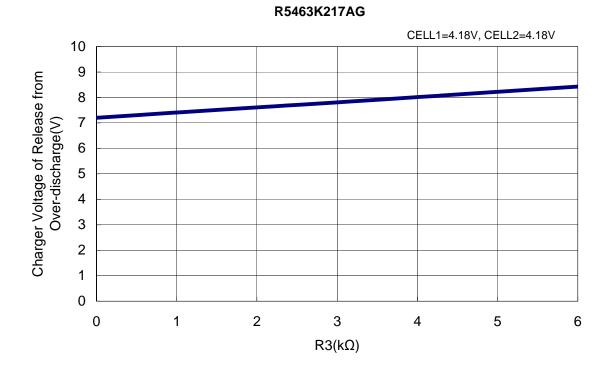
Over-discharge Detector Threshold / Released from Over-discharge Threshold vs. R1 R5463K217AG



Part 5 Charger Voltage at Released from Over-discharge with a Charger dependence on R2



Charger Voltage at Release from Over-discharge with a charger vs. R2





- 1. The products and the product specifications described in this document are subject to change or discontinuation of production without notice for reasons such as improvement. Therefore, before deciding to use the products, please refer to Ricoh sales representatives for the latest information thereon.
- 2. The materials in this document may not be copied or otherwise reproduced in whole or in part without prior written consent of Ricoh.
- 3. Please be sure to take any necessary formalities under relevant laws or regulations before exporting or otherwise taking out of your country the products or the technical information described herein.
- 4. The technical information described in this document shows typical characteristics of and example application circuits for the products. The release of such information is not to be construed as a warranty of or a grant of license under Ricoh's or any third party's intellectual property rights or any other rights.
- 5. The products listed in this document are intended and designed for use as general electronic components in standard applications (office equipment, telecommunication equipment, measuring instruments, consumer electronic products, amusement equipment etc.). Those customers intending to use a product in an application requiring extreme quality and reliability, for example, in a highly specific application where the failure or misoperation of the product could result in human injury or death (aircraft, spacevehicle, nuclear reactor control system, traffic control system, automotive and transportation equipment, combustion equipment, safety devices, life support system etc.) should first contact us.
- 6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
- 7. Anti-radiation design is not implemented in the products described in this document.
- 8. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
- 9. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
- 10. There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact Ricoh sales or our distributor before attempting
- 11. Please contact Ricoh sales representatives should you have any questions or comments concerning the products or the technical information.



Ricoh is committed to reducing the environmental loading materials in electrical devices with a view to contributing to the protection of human health and the environment.

Halogen Free

Ricoh has been providing RoHS compliant products since April 1, 2006 and Halogen-free products since April 1, 2012.

RICOH RICOH ELECTRONIC DEVICES CO., LTD.

https://www.e-devices.ricoh.co.jp/en/

Sales & Support Offices

Ricoh Electronic Devices Co., Ltd.

Shin-Yokohama Office (International Sales)
2-3, Shin-Yokohama 3-chome, Kohoku-ku, Yokohama-shi, Kanagawa, 222-8530, Japan
Phone: +81-50-3814-7687 Fax: +81-45-474-0074

Ricoh Americas Holdings, Inc

way, Suite 200 Campbell, CA 95008, U.S.A. 675 Campbell Technology Part Phone: +1-408-610-3105

Ricoh Europe (Netherlands) B.V.

Semiconductor Support Centre

Prof. W.H. Keesomlaan 1, 1183 DJ Amstelveen, The Netherlands Phone: +31-20-5474-309

Ricoh International B.V. - German Branch

Semiconductor Sales and Support Centre Oberrather Strasse 6, 40472 Düsseldorf, Germany

Phone: +49-211-6546-0

Ricoh Electronic Devices Korea Co., Ltd.

3F, Haesung Bldg, 504, Teheran-ro, Gangnam-gu, Seoul, 135-725, Korea Phone: +82-2-2135-5700 Fax: +82-2-2051-5713

Ricoh Electronic Devices Shanghai Co., Ltd.

Room 403, No.2 Building, No.690 Bibo Road, Pu Dong New District, Shanghai 201203, People's Republic of China

Phone: +86-21-5027-3200 Fax: +86-21-5027-3299

Ricoh Electronic Devices Shanghai Co., Ltd. Shenzhen Branch

1205, Block D(Jinlong Building), Kingkey 100, Hongbao Road, Luohu District,

Shenzhen, China Phone: +86-755-8348-7600 Ext 225

Ricoh Electronic Devices Co., Ltd.

Taipei office
Room 109, 10F-1, No.51, Hengyang Rd., Taipei City, Taiwan
Phone: +886-2-2313-1621/1622 Fax: +886-2-2313-1623

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Ricoh Electronics: